

# AON6278-VB Datasheet N-Channel 85V (D-S) MOSFET

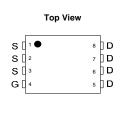
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$V_{DS}(V)$ $R_{DS(on)}(\Omega)$			
85	0.0045at V <sub>GS</sub> = 10 V	80		
	0.0120at V <sub>GS</sub> = 4.5 V	60		

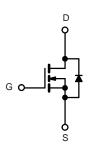
### **FEATURES**

- 150 °C Junction Temperature
- SGT technology Power MOSFET
- Material categorization:









N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
Parameter		Symbol	Limit	Unit		
Gate-Source Voltage		$V_{GS}$	±20	V		
0	T <sub>C</sub> = 25 °C	I-	80			
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>b</sup>	T <sub>C</sub> = 100 °C	- I <sub>D</sub>	64 <sup>a</sup>			
Pulsed Drain Current	I <sub>DM</sub>	240	Α			
Continuous Source Current (Diode Conduction)	I <sub>S</sub>	80 <sup>a</sup>				
Avalanche Current	I <sub>AS</sub>	70				
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E <sub>AS</sub>	133	mJ		
Maximum Power Discinction	T <sub>C</sub> = 25 °C	Pn	136	W		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	' D	3 <sup>b</sup> , 8.3 <sup>b, c</sup>	]		
Operating Junction and Storage Temperature Range	·	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>a</sup>	t ≤ 10 sec	R <sub>thJA</sub>	15	18	°C/W		
Waximum Junction-to-Ambient	Steady State		40	50			
Maximum Junction-to-Case		R <sub>thJC</sub>	0.85	1.1			

#### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c.  $t \le 10$  s.



<b>SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min. Typ. <sup>a</sup>		Max.	Unit	
Static	•			_			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	85			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	2	3	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		$V_{DS} = 30V, V_{GS} = 0 V$			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	50		50	μΑ	
		$V_{DS} = 30V, V_{GS} = 0 V, T_{J} = 150 °C$			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	60			Α	
		$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		0.0045			
Due to Occurre October Destruction	P	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.0067		0	
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 150 °C		0.0090		Ω	
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 46 A		0.0120			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		60		S	
Dynamic							
Input Capacitance	C <sub>iss</sub>			4200			
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 85 \text{ V}, f = 1 \text{ MHz}$		470		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			225			
Total Gate Charge <sup>c</sup>	$Q_g$			92	70		
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 85 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		16		nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			19			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			20	21		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 85 \text{ V}, R_{L} = 0.6 \Omega$		15	25	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		15	20	115	
Fall Time <sup>c</sup>	t <sub>f</sub>			20	30		
Source-Drain Diode Ratings and Ch	aracteristics (	T <sub>C</sub> = 25 °C)					
Pulsed Current	I <sub>SM</sub>				240	Α	
Diode Forward Voltage	$V_{SD}$	$I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$		1	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$			18	ns	

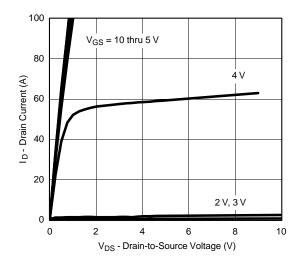
#### Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- c. Independent of operating temperature.

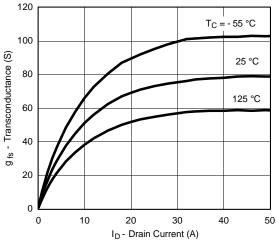
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



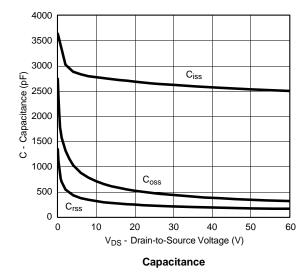
# TYPICAL CHARACTERISTICS (25 °C unless noted)



## **Output Characteristics**



#### Transconductance

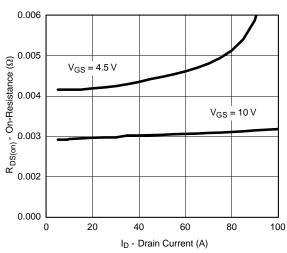


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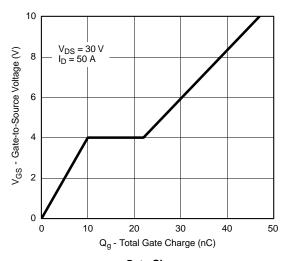
80

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### **Transfer Characteristics**



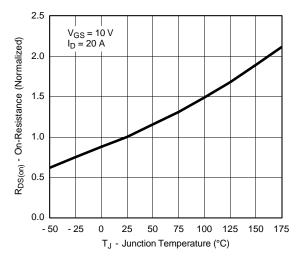
On-Resistance vs. Drain Current



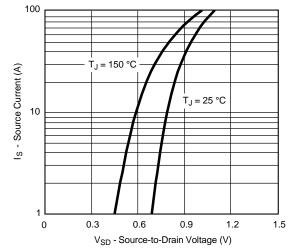
Gate Charge



# TYPICAL CHARACTERISTICS (25 °C unless noted)



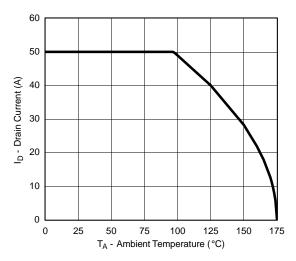
On-Resistance vs. Junction Temperature

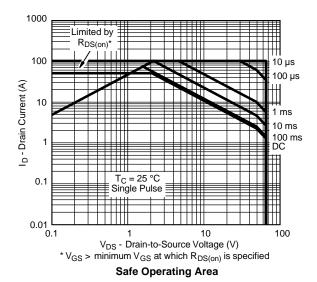


Source-Drain Diode Forward Voltage

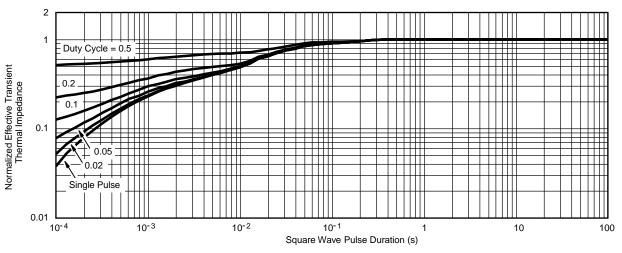


### THERMAL RATINGS





Maximum Drain Current vs. Ambient Temperature



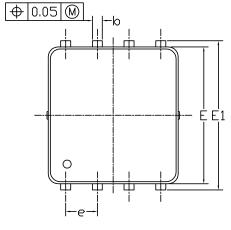
Normalized Thermal Transient Impedance, Junction-to-Case

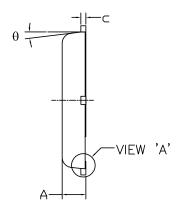
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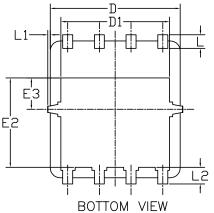
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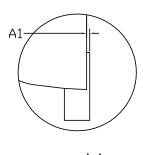


DFN5x6\_8L\_EP1\_P PACKAGE OUTLIN



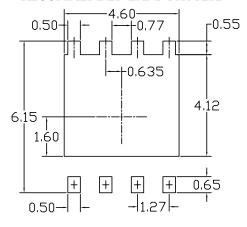






<u>VIEW 'A'</u> (SCALE 5:1)

#### RECOMMENDED LAND PATTERN



GVA (DOLG	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
SYMBOLS	MIN	NOM	MAX	MIN	NOM	MAX
A	0.85	0. 95	1.00	0.033	0.037	0.039
Al	0.00		0.05	0.000		0.002
b	0.30	0.40	0.50	0.012	0.016	0.020
С	0.15	0. 20	0. 25	0.006	0.008	0.010
D	5. 10	5. 20	5. 30	0. 201	0. 205	0. 209
D1	4. 25	4. 35	4. 45	0. 167	0. 171	0. 175
Е	5. 45	5. 55	5. 65	0.215	0.219	0. 222
E1	5. 95	6.05	6. 15	0. 234	0. 238	0. 242
E2	3. 525	3.625	3. 725	0.139	0.143	0. 147
E3	1. 175	1. 275	1.375	0.046	0.050	0.054
e		1.27 BSC			0.050 BSC	
L	0.45	0. 55	0.65	0.018	0.022	0.026
L1	0		0. 15	0		0.006
L2		0.68 REF			0.027 REF	
θ	0°		10°	0°		10°

#### **NOTE**

- 1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS. MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
- 2. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

UNIT: mm



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